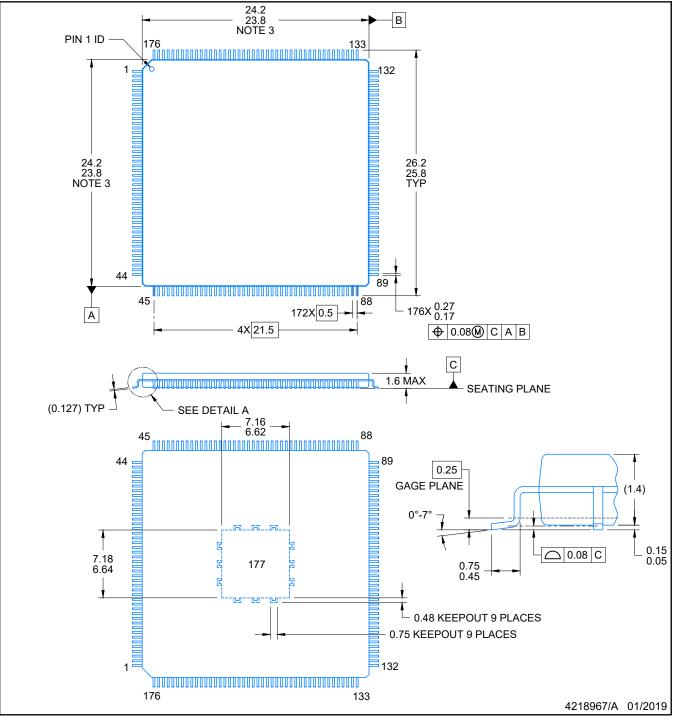
PTP0176E

PACKAGE OUTLINE

HLQFP - 1.6 mm max height

PLASTIC QUAD FLATPACK



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per side.

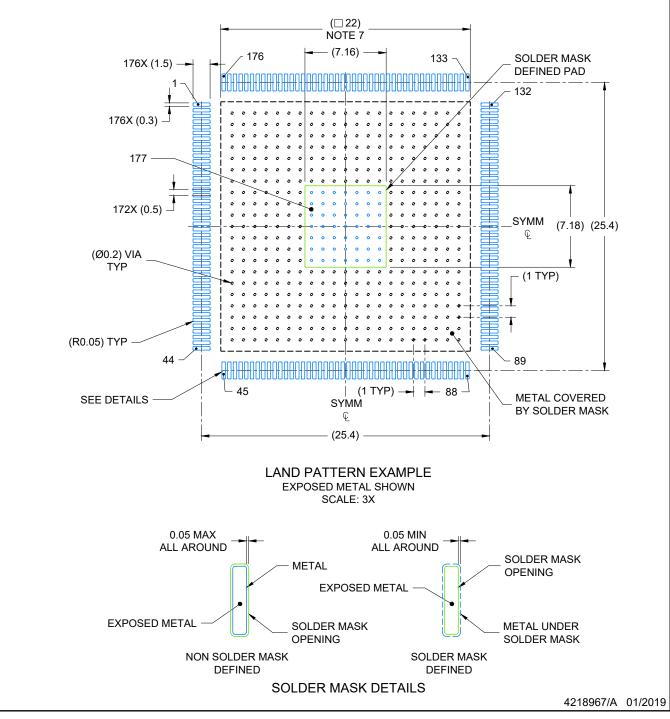


PTP0176E

EXAMPLE BOARD LAYOUT

HLQFP - 1.6 mm max height

PLASTIC QUAD FLATPACK



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
- 7. This package is designed to be soldered to a thermal pad on the board. See technical brief. Powerpad thermally enhanced package, Texas Instruments Literature No. SLMA002 (www.ti.com/lit/slma002) and SLMA004 (www.ti.com/lit/slma004).
- 8. Vias are optional depending on application, refer to device data sheet. It is recommended that vias under paste be filled, plugged or tented.

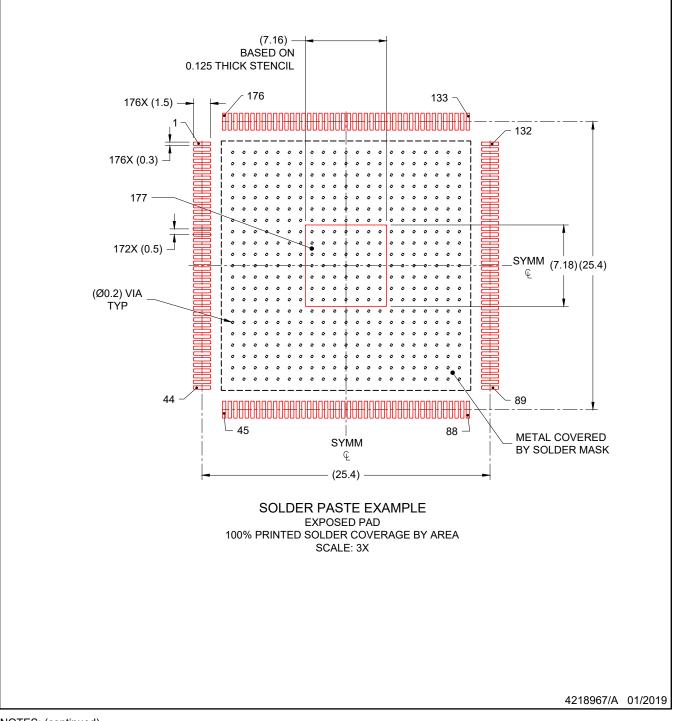


PTP0176E

EXAMPLE STENCIL DESIGN

HLQFP - 1.6 mm max height

PLASTIC QUAD FLATPACK



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



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